# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**

[List multiple models if applicable.]

HP RP5 Retail System, Model 5810

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cmApollo PCA board/Riser card board/ PSU PCA board/12V USB card board/Power serial card board/2nd DP card board/COM_B card board</td>
<td>7</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Chicony PSU</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>SW5 x 125</td>
<td>5.0</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Disconnect the cables from fan duct and the MB.(see Figure 2-6 below)
3. Remove ODD or HDD from chassis.(see Figure 7-12 below)
4. Remove PSU from chassis.(see Figure 13 below)
5. Remove the Riser card and powered serial port card from the MB(see Figure 14-18 below)
6. Remove the 12V powered USB card from the MB(see Figure 19-22 below)
7. Remove front bezel from chassis.(see Figure 23 below)
8. Remove front system fan from chassis.(see Figure 24-26 below)
9. Remove FIO and speaker from chassis.(see Figure 27-29 below)
10. Remove the Memory from the board.(see Figure 30 below)
11. Remove the CPU from the board.(see Figure 31-33 below)
12. Remove the battery from the system board.(see Figure 34 below)
13. Remove the COMB card from the MB.(see Figure 35 below)
14. Remove M/B from chassis.(see Figure 36-37 below)
15. Remove PSU cover.(see Figure 38-39 below)
16. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 40-50 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel

Figure 2 Disconnect the cables from fan duct

Figure 3 Remove fan duct from the board

Figure 4 Disconnect SATA cables from the MB
Figure 5 Disconnect CPU Power cable from the MB

Figure 6 Disconnect other PSU cables from the MB

Figure 7 Disconnect SATA cable from ODD

Figure 8 Disconnect SATA cable from HDD

PSG instructions for this template are available at EL-MF877-01
Figure 9 Press the ODD’s latch on ODD cage

Figure 10 Remove the ODD from cage

Figure 11 Press the HDD’s latch on HDD cage

Figure 12 Remove the HDD from cage

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 13 Remove the PSU from Cage

Figure 14 Open the Full height PCI latch cover

Figure 15 Move the full height slot cover

Figure 16 Remove the powered serial port card from full height slot
Figure 17 Remove the hood sensor cable from MB

Figure 18 Remove the Riser card from MB

Figure 19 Remove the 12V powered USB card cable from MB

Figure 20 Open the half height PCIe latch cover

PSG instructions for this template are available at EL-MF877-01
Figure 21 Remove the 2nd 12V powered USB card from MB

Figure 22 Remove the 1st 12V powered USB card from MB

Figure 23 Remove front panel

Figure 24 Disconnect front system fan cable from MB
Figure 25 Loose the front system fan holder hook from chassis

Figure 26 Remove front system fan holder

Figure 27 Disconnect FIO cables from MB

Figure 28 Loose screw of FIO and remove FIO
Figure 29: Loose screws of speaker and remove speaker.

Figure 30: Remove the Memory from MB.

Figure 31: Loose the screws and remove heat sink.

Figure 32: Rotate CPU socket handle and open it up.

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01).
Figure 33 Remove the CPU from MB

Figure 34 Remove the battery from MB

Figure 35 Loose the screws of COMB card and remove

Figure 36 Loose MB screws from chassis
Figure 37 Remove M/B from chassis

Figure 38 Remove the screws on the PSU chassis

Figure 39 Lift the cover off the power supply

Figure 40 Remove the four screws on the board

PSG instructions for this template are available at EL-MF877-01
Figure 41 Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove them

Figure 42 Remove the power supply cable from the power supply

Figure 43 Heat the solder of Electrolytic Capacitors

Figure 44 Remove the Electrolytic Capacitors

Figure 45 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height

Figure 46 Remove the Electrolytic Capacitors (For Acbel 240W EPA)
<table>
<thead>
<tr>
<th>Figure 47 Remove the Electrolytic Capacitors (For Liteon EPA PSU)</th>
<th>Figure 48 Remove the Electrolytic Capacitors (For Delta EPA PSU)</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.png" alt="Image" /></td>
<td><img src="image2.png" alt="Image" /></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 49 Remove the Electrolytic Capacitors (For Chicony EPA PSU)</th>
<th>Figure 50 Remove the Electrolytic Capacitors (For Bestec EPA PSU)</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image3.png" alt="Image" /></td>
<td><img src="image4.png" alt="Image" /></td>
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